

03/21/2011



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To the Director of the U.S. Patent and Trademark Office. Please record the attached documents or the new address(es) below.

3-21-11

1. Name of conveying party(ies)

Tohoku University

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name Advanced Interconnect Materials, LLC

Internal Address \_\_\_\_\_

Street Address 6-6-40-402, Aza-aoba, Aramaki

Aoba-ku

City Sendai-shi

State Miyagi

Country Japan Zip 980-0845

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) February 7, 2011

- Assignment  Merger
- Security Agreement  Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other \_\_\_\_\_

4. Application or patent number(s):

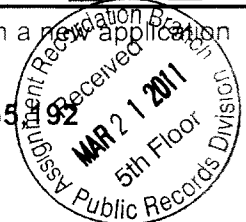
This document is being filed together with a new application

A Patent Application No (s) \_\_\_\_\_

B Patent No (s)

7,633,164, 7,642,552, 7,755,782, 7,782,413, 7,782,433

Additional numbers attached?  Yes  No



5. Name and address to whom correspondence concerning document should be mailed:

Name Peter Martinez, Masuvalley & Partners

Internal Address \_\_\_\_\_

Street Address 8765 Aero Drive, Suite 312

City San Diego

State CA Zip 92123

Phone Number 858-715-6858

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Email Address: docketing@masuvalley.com

6. Total number of applications and patents involved: 5

7. Total fee (37 CFR 1.21(f) & 3.41) \$200

- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

Deposit Account Number 03/21/2011 KNGUYEN1 00000002 7633164

Authorized Person's Name \_\_\_\_\_ 200.00 00

9. Signature:

Peter Martinez  
Signature

3-5-2011  
Date

Peter Martinez

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents

3

## ASSIGNMENT

WHEREAS, Tohoku University, hereinafter referred to as ASSIGNOR, a Japanese Educational Institution duly organized under the law of Japan, is, by virtue of assignments recorded at the United States Patent and Trademark Office, the co-owner of the entire right, title and interest in the invention(s) described and claimed in the following:

1. United States Letters Patent No.: **7,633,164**  
Entitled: "LIQUID CRYSTAL DISPLAY DEVICE AND MANUFACTURING METHOD THEREFOR"
2. United States Letters Patent No.: **7,642,552**  
Entitled: "LIQUID CRYSTAL DISPLAY DEVICE AND MANUFACTURING METHOD THEREFOR"
3. United States Letters Patent No.: **7,755,192**  
Entitled: "COPPER INTERCONNECTION STRUCTURE, SEMICONDUCTOR DEVICE, AND METHOD FOR FORMING COPPER INTERCONNECTION STRUCTURE"
4. United States Letters Patent No.: **7,782,413**  
Entitled: "LIQUID CRYSTAL DISPLAY DEVICE AND MANUFACTURING METHOD THEREFOR"
5. United States Letters Patent No.: **7,782,433**  
Entitled: "COPPER ALLOY AND LIQUID-CRYSTAL DISPLAY DEVICE"

WHEREAS, Advanced Interconnect Materials, LLC, hereinafter referred to as ASSIGNEE, a corporation duly organized under the laws of Japan and having its principal place of business at 6-6-40-402, Aza-aoba, Aramaki, Aoba-ku, Sendai-shi, Miyagi 980-0845, Japan, is desirous of acquiring the entire right, title and interest as held by ASSIGNOR in, to and under the said Letters Patents, and the inventions embodied therein:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: be it known that in consideration of a prior payment by ASSIGNEE to ASSIGNOR, the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR hereby sells, assigns, and transfers to ASSIGNEE, its entire right, title, and interest in and to said Letters Patent(s) and the invention(s) therein, for the full term of the said Patents and any subsequent patents thereof.

IN WITNESS WHEREOF, the undersigned ASSIGNOR has hereunto set hand and seal  
this 7 day of Feb., 2011.

Assignor: Tohoku University

Signature of Representative: Hiroshi Kazui

Name: Hiroshi KAZUI

Title: Executive Vice President for Industry-University  
Cooperation